ZENIMID™ POLYIMIDES | RILSAMID® PA12 | RILSAN® PA11 | KYNAR® PVDF

ADVANCED MATERIALS FOR **DATA CENTER COOLING SYSTEMS**

Combining complementary polymer technologies for modern cooling infrastructure challenges.

ARKEMA MATERIAL SOLUTIONS

ZENIMID™

Support advanced heat-spreading solutions and thermal management systems where electrical insulation and thermal stability are critical.

RILSAN®

Lightweight and durable bio-based **Polyamide 11** for cooling circuits, tubing, and connectors.

RILSAMID®

Reliable **Polyamide 12** for tubing, connectors, and fluid handling systems requiring durability and long-term performance.

KYNAR®

High-performance **PVDF** offering chemical resistance and long-term reliability in demanding cooling environments.

WHERE ADVANCED MATERIALS ARE USED?

- → **Cooling fluid handling and distribution**
- → **Tubing, valves, and quick connectors**
- → **Cooling plates and cold plates**
- → **Heat spreading and thermal interface systems**
- → **High-density electronics cooling**

WHY ADVANCED MATERIALS MATTER FOR DATA CENTER COOLING?

- → **Support efficient heat removal in high-power-density architectures**
- → **Enable reliable fluid transport and distribution throughout cooling systems**
- → **Maintain performance in thermal and chemically demanding operating conditions**
- → **Provide insulation and protection for sensitive electronic equipment**
- → **Support advanced cooling technologies and heat-transfer solutions**
- → **Deliver long-term reliability under continuous operation**

DESIGNED FOR DEMANDING DATA CENTER COOLING ENVIRONMENTS

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